

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED



MBRS130LT3G(MS)

Product specification

Reference News

FEATURES

- The plastic package carries underwriters Laboratory Flammability classification 94v-0
- For surface mounted applications
- Metal silicon junction , majority carrier conduction
- Low power loss , high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Compliant to ROHS Directive 2011/65/EU
- Compliant to Halogen-free

Outline	Marking
	
SMB	

MECHANICAL DATA

- **Case:** JEDEC DO-214AA molded plastic body
- **Terminals:** solder plated , solderable per MIL-STD-750 , Method 2026
- **Polarity:** color band denotes cathode end
- **Mounting Position:** Any

Maximum ratings and Electrical characteristics (AT T_A= 25°C unless otherwise noted)

PARAMETER	SYMBOLS	MBRS130LT3G(MS)	UNITS
Maximum repetitive peak reverse voltage	V _R RM	30	V
Maximum RMS voltage	V _R MS	30	V
Maximum DC blocking voltage	V _D C	30	V
Maximum average forward rectified current at T _L (see fig.1)	I _(AV)	2.0	A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I _F SM	50	A
Maximum instantaneous forward voltage at 1.0A	V _F	0.39	V
Maximum instantaneous forward voltage at 2.0A	V _F	0.44	
Maximum DC reverse current at rated DC blocking voltage T _A =25°C T _J =85°C	I _R	0.1	mA
		10.0	
Typical junction capacitance (NOTE 1)	C _J	200	pF
Typical thermal resistance (NOTE 2)	R _θ JA	60	°C/W
Operating junction temperature range	T _J	-55 to +150	°C
Storage temperature range	T _{STG}	-55 to +150	°C

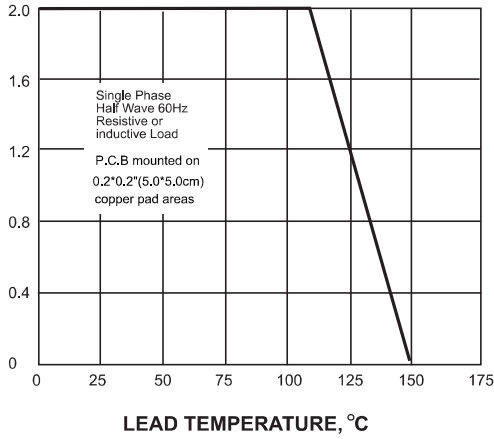
Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. P.C.B. mounted with 2.0x2.0"(5.0x5.0cm) copper pad areas

Rating and characteristic curves

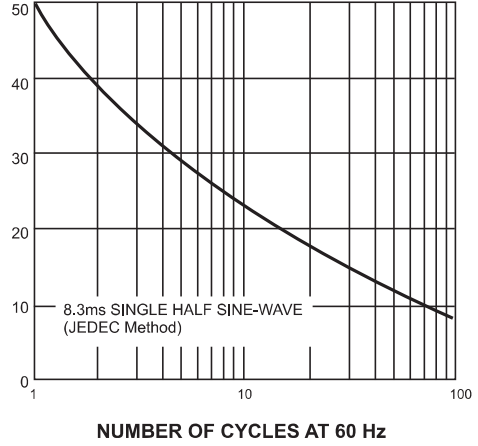
AVERAGE FORWARD RECTIFIED CURRENT,
AMPERES

FIG. 1- FORWARD CURRENT DERATING CURVE



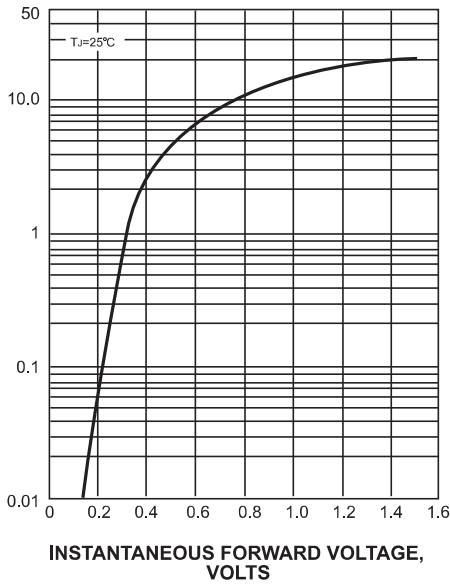
PEAK FORWARD SURGE CURRENT,
AMPERES

FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



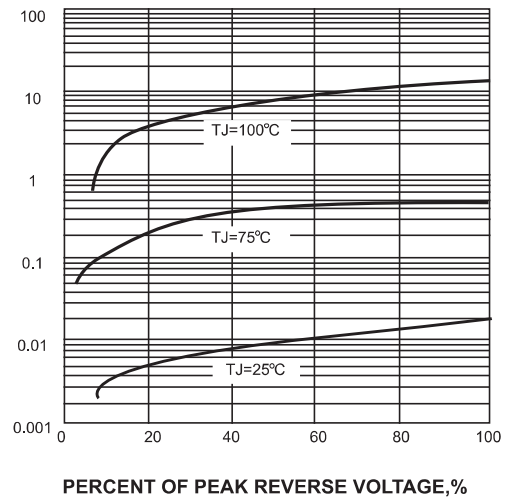
INSTANTANEOUS FORWARD CURRENT, AMPERES

FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS



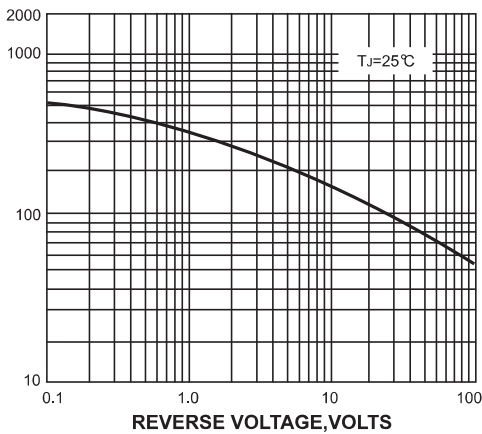
INSTANTANEOUS REVERSE CURRENT, MILLIAMPERES

FIG. 4-TYPICAL REVERSE CHARACTERISTICS



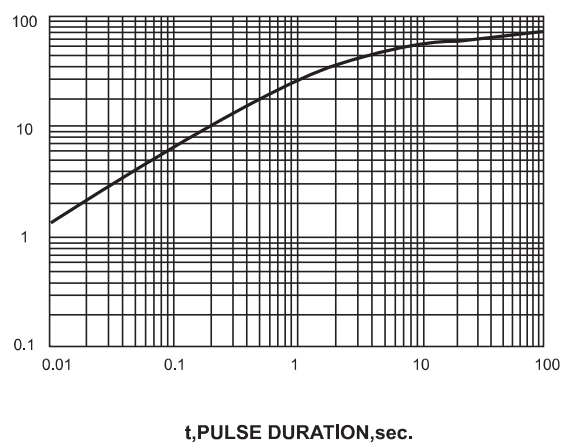
JUNCTION CAPACITANCE, pF

FIG. 5-TYPICAL JUNCTION CAPACITANCE



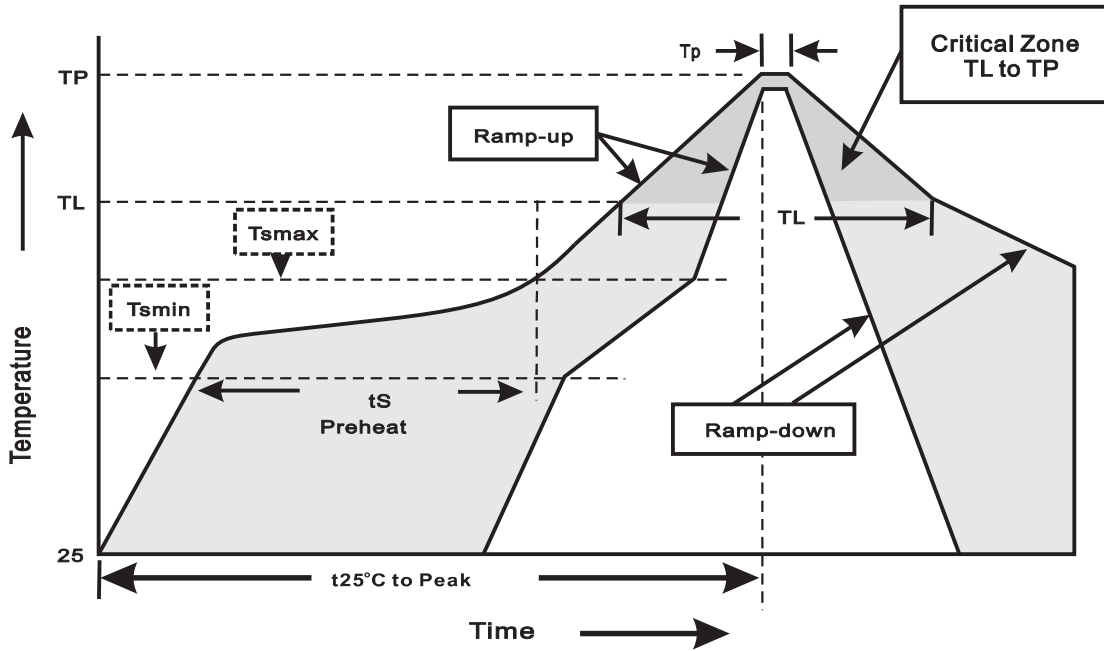
TRANSIENT THERMAL IMPEDANCE, °C/W

FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



Suggested thermal profiles for soldering processes

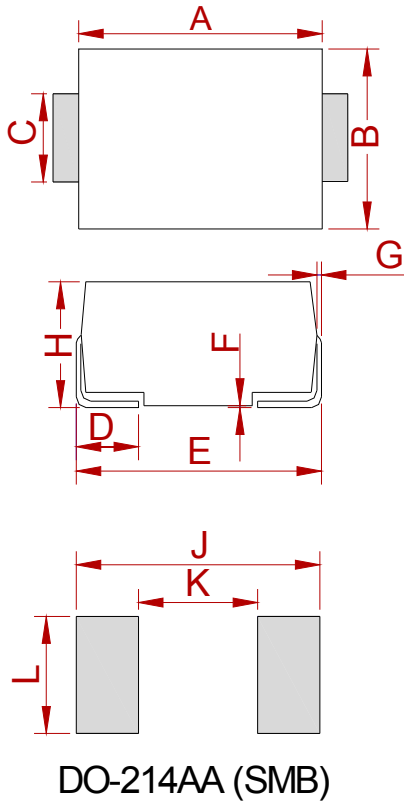
- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

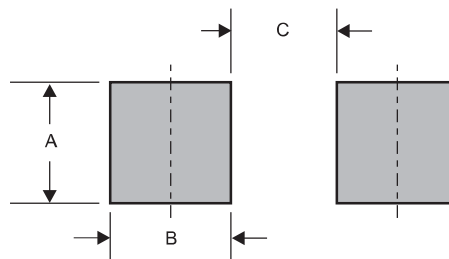
Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smin}) -Temperature Max(T _{smax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

PACKAGE MECHANICAL DATA



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.75	0.167	0.187
B	3.30	3.94	0.130	0.155
C	1.85	2.21	0.073	0.087
D	0.76	1.52	0.030	0.060
E	5.08	5.59	0.200	0.220
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	2.11	2.44	0.083	0.096
J	6.80		0.270	
K		2.60		0.100
L	2.40		0.090	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.078 (2.00)	0.059 (1.50)	0.110 (2.80)

REEL SPECIFICATION

P/N	PKG	QTY
MBRS130LT3G(MS)	SMB	3000

Attention

- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Schottky Diodes & Rectifiers](#) category:

Click to view products by [MSKSEMI](#) manufacturer:

Other Similar products are found below :

[MA4E2039](#) [MMBD301M3T5G](#) [RB160M-50TR](#) [D83C](#) [BAS16E6433HTMA1](#) [BAS 3010S-02LRH E6327](#) [BAT 54-02LRH E6327](#)
[NRVBAF360T3G](#) [NSR05F40QNXT5G](#) [NTE555](#) [JANS1N6640](#) [SS3003CH-TL-E](#) [GA01SHT18](#) [CRS10I30A\(TE85L,QM](#) [MBRA140TRPBF](#)
[MBRB30H30CT-1G](#) [BAT 15-04R E6152](#) [JANTX1N5712-1](#) [DMJ3940-000](#) [SB007-03C-TB-E](#) [NRVBB20100CTT4G](#) [NRVBM120LT1G](#)
[NTSB30U100CT-1G](#) [CRG04\(T5L,TEMQ\)](#) [ACDBA1100LR-HF](#) [ACDBA1200-HF](#) [ACDBA240-HF](#) [ACDBA3100-HF](#) [CDBQC0530L-HF](#)
[ACDBA260LR-HF](#) [ACDBA1100-HF](#) [10BQ015-M3/5BT](#) [NRVBM120ET1G](#) [VSSB410S-M3/5BT](#) [1N5819T-G](#) [PDS1040Q-13](#) [B160BQ-13-F](#)
[SDM05U20CSP-7](#) [BAS 70-07 E6433](#) [B140S1F-7](#) [HSM560Je3/TR13](#) [DDB2265-000](#) [ZHCS506QTA](#) [HSM190Je3/TR13](#) [B330AF-13](#)
[ACDBUC0230-HF](#) [SDM1U100S1F-7](#) [MBR10200CTF-G1](#) [CDLL5712](#) [DMF2822-000](#)